

#2 / Per Amet A
4-11-20
R. Stuber

DOCKET NO.: EN9-98-117-US2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Buchwalter et al.

Examiner:

Serial No.:

Art Unit:

Filed:

For: CAP ATTACH SURFACE MODIFICATION FOR IMPROVED ADHESION

Commissioner for Patents
Washington D.C. 20231

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination.

In the Specification:

Page 1, between lines 1 and 2, insert: ~This application is a divisional of Serial No.

09/361,723, filed on July 27, 1999 ^{now U.S. PAT. No. 6,369,452}

In the Claims:

Please cancel claims 1-9. The following claims 10-29 are currently pending.

10. A method for forming an electronic structure, comprising:

providing a metallic plate;

forming a mineral layer on the metallic plate; and

forming an adhesion promoter layer on the mineral layer.